IEEE International
3D System Integration Conference
3D-IC 2026

Call for Papers

October 2026

The IEEE International 3D Systems Integration Conference is a peer-reviewed conference that aims to bring together 3D researchers from academia, government, and industry. 3DIC'26 invites high-quality novel research paper submissions that focus on 3D methodological and application perspectives.

Location: This year's IEEE International 3D System Integration Conference (3DIC 2026) will be held at **Georgia Institute of Technology, Atlanta.**

Topics Areas:

Papers are solicited on all 3D IC topics including, but not limited to, the following:

Technology: Materials, equipment, wafer handling, diverse substrates, Through Silicon Vias (TSV), alignment, bonding (thermo-compression, electrostatic, hybrid, temporary adhesive), de-bonding, wafer cleaning, thinning, dicing, chiplets, interposers (active, passive), 3D integration (monolithic, heterogeneous), capacitive coupling, inductive coupling, multilevel epitaxial growth, etc.

Applications, Design and Computer Aided Design (CAD): Synthesis, design flows, signal design, power integrity, thermal considerations, mechanical stress, reliability, test, techniques, analysis, chiplet and chiplet design etc. Applications to be considered may include imaging, memory, processors, communications, networking, wireless, biomedical, sensors, SOC, MEMS, DSP, FPGA, RF, microwave, millimeter wave, analog circuits, biomedical circuits, photonics, optoelectronics, etc. Application areas such quantum computing, embedded systems, artificial intelligence and others.

Paper Submissions:

- **Deadline:** Presentation abstracts may be submitted on the conference website between July 1st and July 31
- **Submission Website:** www.3dic-conf.org.
- **Length and Format:** Abstracts should be about 500 words in length; some figures and tables can be included. Notifications will occur by August 31 and full papers in IEEE format will be required by September 30, 2026.

Workshop and Tutorials:

3D-IC'26 is seeking high quality workshop and tutorial proposals in the areas of 3D Integration technology, applications, design and computer aided design areas. To propose an idea for a tutorial please contact the conference organizers (rpatti@nhanced-semi.com, ekurshan@ieee.org).